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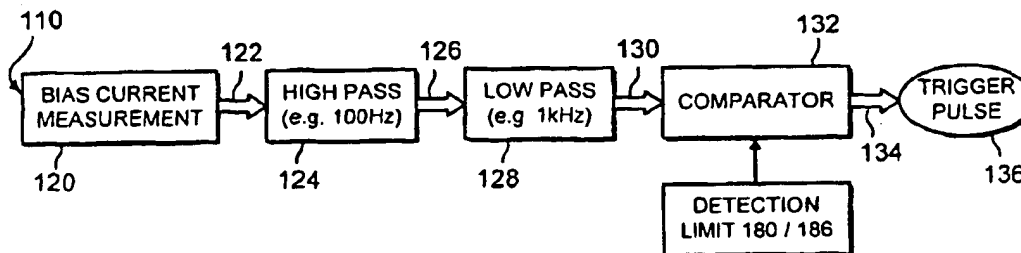
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(54) Title: SELF TRIGGERED IMAGING DEVICE FOR IMAGING RADIATION



DIFFERENTIAL (EDGE) DETECTION

(57) Abstract

A semiconductor radiation imaging assembly comprises a semiconductor imaging device including at least one image element detector. The imaging device is arranged to receive a bias for forming the at least one image element detector. The assembly also includes bias monitoring means for monitoring the bias for determining radiation incident on the image element detector. Preferably, the imaging device comprises a plurality of image element detectors the bias for at least some of which is monitored for determining incident radiation. More preferably, the bias for all the detector elements is monitored.